

Acteev™ AP NT0809

polyamide 66



Acteev AP NT0809 is an antimicrobial and antifungal, general purpose, lubricated PA66 resin with an enhanced crystallization temperature. AP NT0809 is designed to offer high strength and rigidity, while being protected from degradation caused by bacteria and fungi.

Regional Availability

General	•			
Additive	• Lubricant			
Features	• Excellent Processability • Lubricated	• Fast Molding Cycle • Nucleated	• Good Strength	
Agency Rating	• ASTM, D4066 PA0131	• ASTM, D6779 PA0131	• ISO, 1043 PA66	
Appearance	• Natural Color			
Forms	• Pellets			
Processing Method	• Injection Molding			

Physical	dry	cond.	Unit	Test Standard
Density	1.14	-	g/cm ³	ISO 1183
Molding Shrinkage				ISO 294-4
Across Flow : 23°C, 2.00 mm	1.6	*	%	
Flow : 23°C, 2.00 mm	1.6	*	%	
Water Absorption				ISO 62
23°C, 24 hr	2	*	%	
Equilibrium, 23°C, 50% RH	2.4	*	%	

Mechanical	dry	cond.	Unit	Test Standard
Tensile Modulus (23°C)	3100	1600	MPa	ISO 527-2
Tensile Stress (Yield, 23°C)	85	58	MPa	ISO 527-2
Tensile Stress (Break, 23°C)	52	48	MPa	ISO 527-2
Tensile Strain (Yield, 23°C)	4.9	18	%	ISO 527-2
Tensile Strain (Break, 23°C)	18	>50	%	ISO 527-2
Flexural Modulus (23°C)	3200	1400	MPa	ISO 178
Flexural Strength (23°C)	98	35	MPa	ISO 178

Impact	dry	cond.	Unit	Test Standard
Charpy Notched Impact Strength				ISO 179/1eA
+23°C	4.6	15	kJ/m ²	
-30°C	4.4	5.2	kJ/m ²	
-40°C	3.5	4	kJ/m ²	
Charpy Unnotched Impact Strength				ISO 179/1eU

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+23°C	N	N	kJ/m²
-30°C	N	N	kJ/m²
-40°C	N	N	kJ/m²
Notched Izod Impact Strength			
			ISO 180/1A
+23°C	4.5	13	kJ/m²
-30°C	4.5	7	kJ/m²
-40°C	4.3	7	kJ/m²

Thermal	dry	cond.	Unit	Test Standard
Heat Deflection Temperature				ISO 75-2/A
1.80 MPa, Unannealed	75	-	°C	
0.45 MPa, Unannealed	225	-	°C	
Melting Temperature	260	*	°C	ISO 11357-3

Electrical	dry	cond.	Unit	Test Standard
Dielectric Strength (1.00 mm)	29	28	kV/mm	IEC 60243

Injection	Value	Unit
Drying Temperature	60 - 80	°C
Drying Time	1 - 3	h
Rear Temperature	260 - 280	°C
Middle Temperature	270 - 285	°C
Front Temperature	280 - 290	°C
Nozzle temperature	280 - 300	°C
Processing (Melt) Temperature	285 - 300	°C
Mold Temperature	65 - 95	°C